JST40P40T2-Q

-40V P- Channel Mosfet

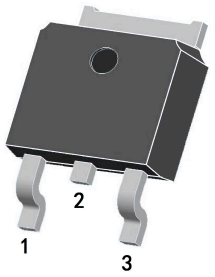
FEATURES

- $R_{DS(ON)}$ ≤ 13mΩ (10mΩ Typ.) @V_{GS}=10V
- $R_{DS(ON)}$ ≤ 22mΩ (15mΩ Typ.) @V_{GS}=4.5V
- AEC Q101 qualified
- Green Product (RoHS compliant)
- 100% UIS TEST

APPLICATIONS

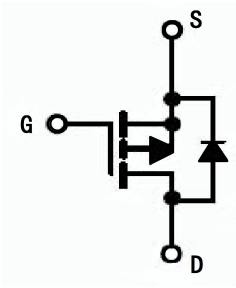
- Automotive Window motor controller
- Load Switch
- PWM Application
- Power management

TO-252



1: G
2: D
3: S

P- CHANNEL MOSFET



Maximum ratings (TC=25℃ unless otherwise noted)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-40	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Continuous Drain Current	T_C = 25℃	-40	A
		T_C = 100℃	-26	A
I_{DM}	Pulsed Drain Current note1		-160	A
E_{AS}	Single Pulsed Avalanche Energy note2		144	mJ
P_D	Power Dissipation	T_C = 25℃	41.6	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.6	℃/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	℃

Electrical Characteristics (T_J=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D= -250μA	-40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}= -40V, V_{GS}=0V	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS}=0V, V_{GS}= ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D= -250μA	-1.0	-1.7	-2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	V_{GS}= -10V, I_D= -20A	-	10	13	mΩ
		V_{GS}= -4.5V, I_D= -10A	-	15	22	
Dynamic Characteristics note4						
C_{iss}	Input Capacitance	V_{DS}= -20V, V_{GS}=0V, f=1.0MHz	-	3800	-	pF
C_{oss}	Output Capacitance		-	329	-	pF
C_{rss}	Reverse Transfer Capacitance		-	289	-	pF
Q_g	Total Gate Charge	V_{DS}= -20V, I_D= -20A, V_{GS}= -10V	-	68	-	nC
Q_{gs}	Gate-Source Charge		-	10	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	14	-	nC
Switching Characteristics note4						
$t_{d(on)}$	Turn-on Delay Time	V_{DD}= -20V, I_D= -20A, V_{GS}= -10V, R_{GEN}=2.4Ω	-	10	-	ns
t_r	Turn-on Rise Time		-	82	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	93	-	ns
t_f	Turn-off Fall Time		-	74	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-40	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-160	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS}=0V, I_S= -30A	-	-0.8	-1.2	V
trr	Reverse Recovery Time	V_{GS}=0V, I_S= -30A, di/dt=100A/μs	-	20	-	ns
Qrr	Reverse Recovery Charge		-	13	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J= 25℃, V_{DD}= -20V, V_G= -10V, L= 0.5mH, R_G= 25Ω, I_{AS}= -24A
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%
4. Guaranteed by design, not subject to production testing

Typical Performance Characteristics

Figure1: Output Characteristics

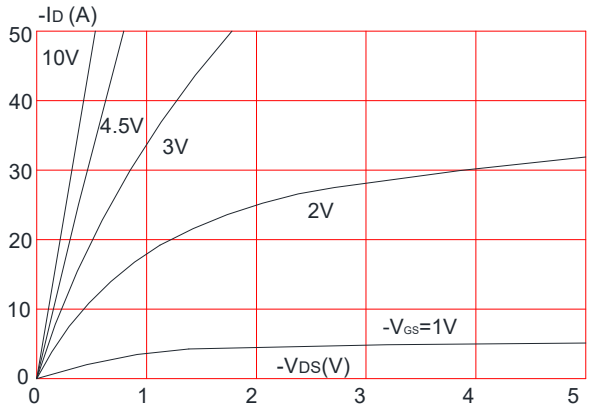


Figure 2: Typical Transfer Characteristics

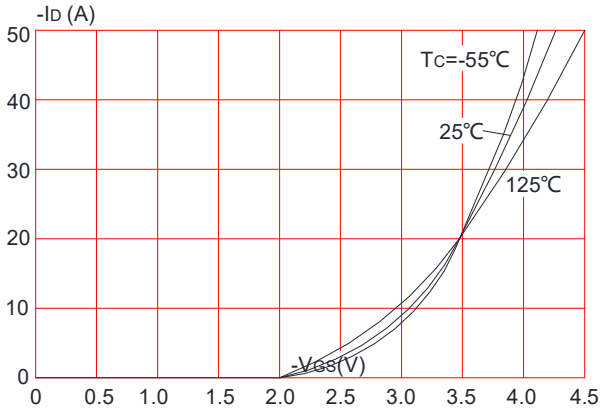


Figure 3: On-resistance vs. Drain Current

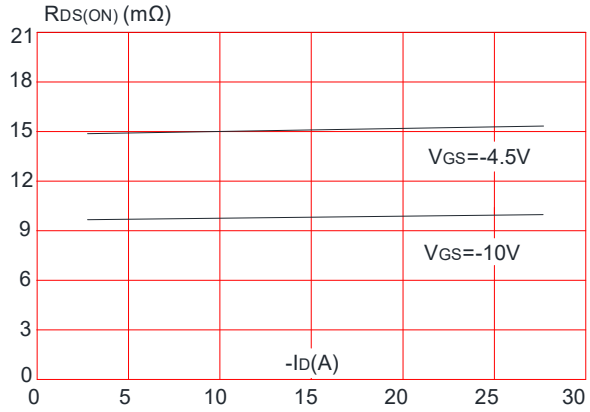


Figure 4: Body Diode Characteristics

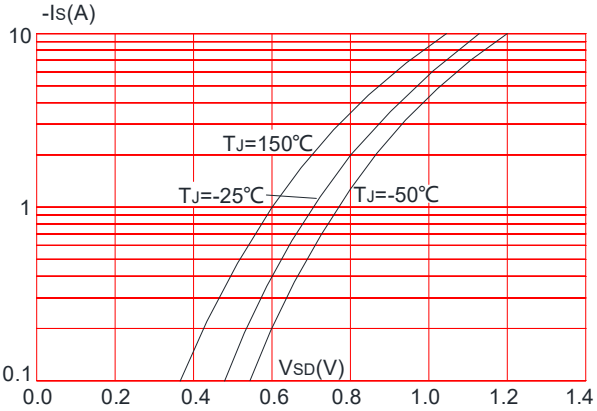


Figure 5: Gate Charge Characteristics

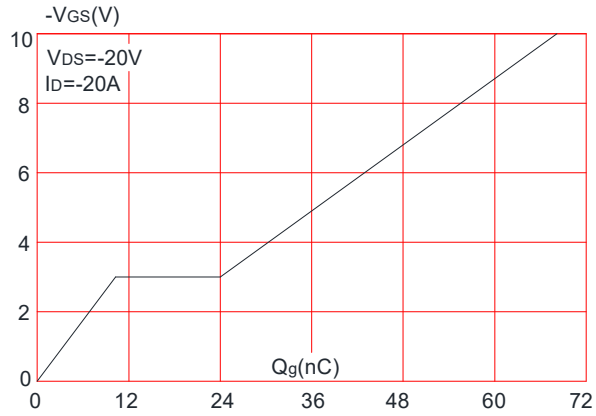
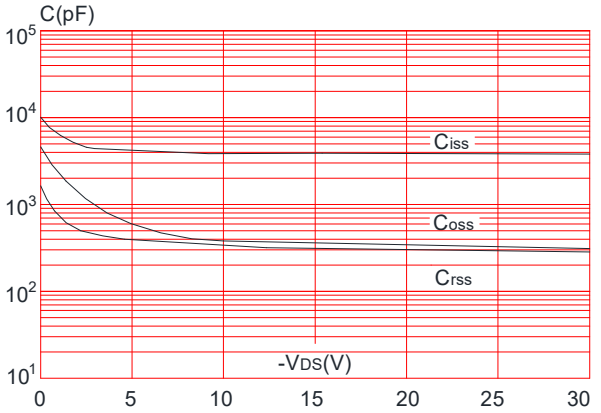


Figure 6: Capacitance Characteristics



Typical Performance Characteristics (cont.)

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

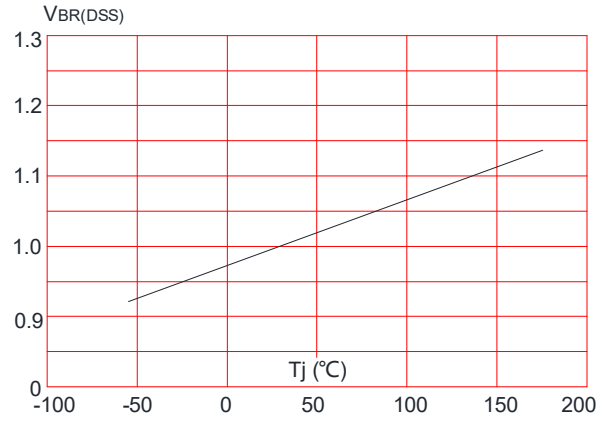


Figure 8: Normalized on Resistance vs. Junction Temperature

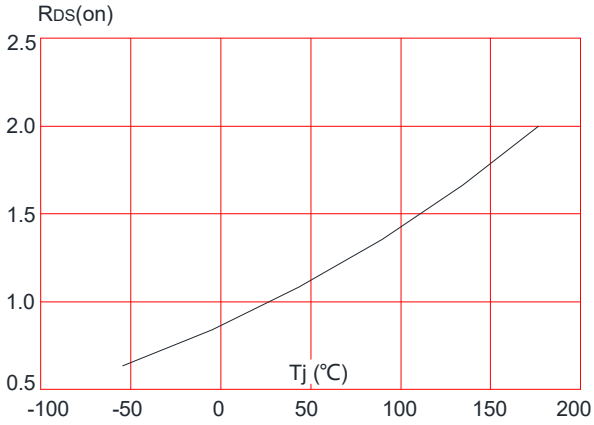


Figure 9: Maximum Safe Operating Area

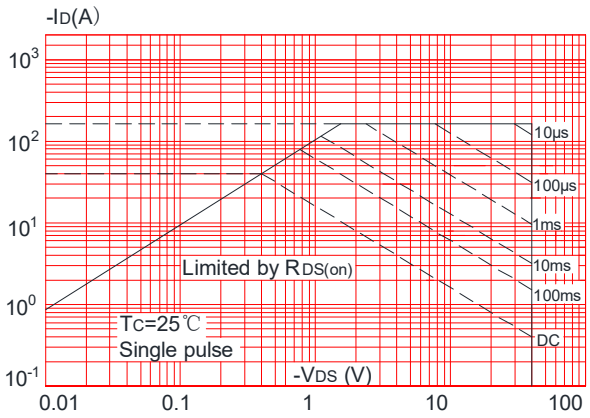


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

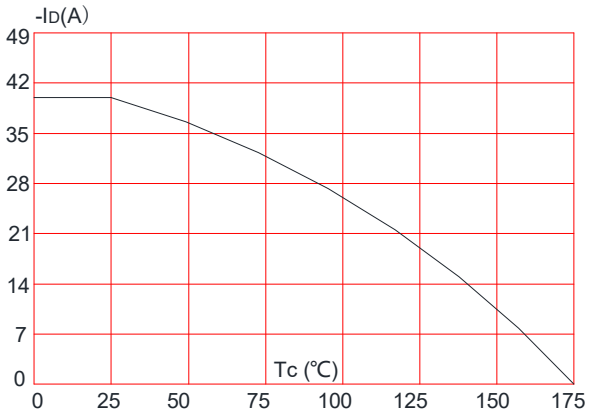
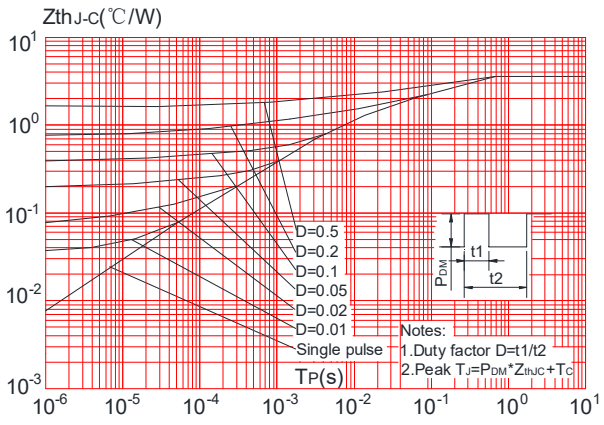
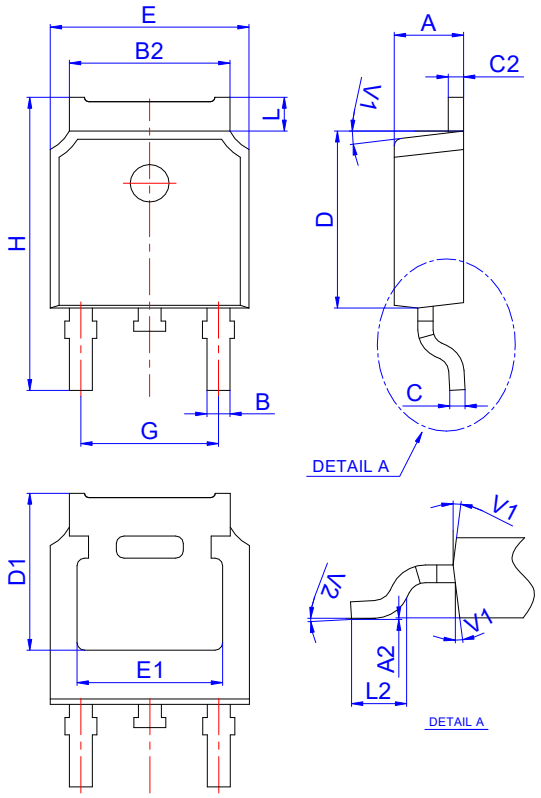


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



TO-252 PACKAGE OUTLINE DRAWING



Symbols	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°